CLAIMS

Claim 1. A photocurable resin sheet, comprising a high molecular compound (A) and a low molecular compound (B);

wherein the high molecular compound (A) has a weight average molecular weight of 1,000 to 1,000,000;

wherein the low molecular compound (B) has a molecular weight of less than 1,000;

wherein the amount of the high molecular compound (A) in the photocurable resin sheet is 85% by mass or more;

wherein the high molecular compound (A) has a glass transition temperature (Tg) of -20°C or higher;

wherein an epoxy group, an oxetanyl group, and a photopolymerization initiating group are each individually present in the high molecular compound (A) or the low molecular compound (B); and

wherein the low molecular compound (B) comprises a compound containing an oxetanyl group.

Claim 2. The photocurable resin sheet according to claim 1,

wherein the photocurable resin sheet has a storage modulus G' at 25°C of 50,000 Pa or higher.

Claim 3. The photocurable resin sheet according to claim 1or 2,

wherein a cured product of the photocurable resin sheet at 25°C has an optical transmittance at a wavelength of 400 nm of 70% or higher and a refractive index with respect to light at a wavelength of 589 nm of 1.40 or higher.

Claim 4. The photocurable resin sheet according to any one of claims 1 to 3,

wherein the high molecular compound (A) comprises at least one selected from the group consisting of poly(meth)acrylic resins, phenoxy resins, polyurethane resins, silicone resins, polyester resins, polyamide resins, and polyimide resins.

Claim 5. The photocurable resin sheet according to any one of claims 1 to 4,

wherein the low molecular compound (B) comprises a photoacid generator.

Claim 6. An optical material obtained by curing the photocurable resin sheet according to any one of claims 1 to 5.